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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Swee Hin Teoh, Dietmar Werner Hutmacher, Kim Cheng Tan, Kock Fye Tam

and Iwan Zein

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Three-Dimensional Bioresorbable Scaffolds for Tissue Engineering

Applications

A 22313-1450, or is being fa nd Trademark Office on:	sioner for Patenta, P.O. Box 1450, Afexandria, estimile transmitted to the United States Patent
Date	Signature

STATEMENT OF FACTS

I, Norliza Ismail, hereby declare and state that:

- I am the Management Assistant Officer from NUS Industry Liaison Office who 1. attempted to contact Inventor Iwan Zein on behalf of the Applicant, Osteopore International Ltd., for the referenced application.
- 2. A registered letter containing a Declaration Under 37 C.F.R. § 1.132 was sent to the last known address of Inventor Iwan Zein on 25 March 2010. The letter was returned by the carrier as undelivered. A copy of the mailing envelope, Speedpost tracking receipt and carrier-stamped reason for non-delivery is attached as Exhibit A (2 pages).
- On, or about, 31 March 2010, I attempted to locate the current address and contact 3. information for Inventor Iwan Zein using Google and White Pages internet searches in Singapore. No current information was found.
- 4. On, or about, 31 March 2010, co-inventors Dietmar Hutmacher, Teoh Swee Hin, Tam Kock Fye and Tan Kim Cheng were contacted and asked if current contact information or whereabouts of Inventor Iwan Zein was known. None of the co-

inventors expressed knowledge of Inventor Iwan Zein's current contact information or whereabouts.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Norliza	Ist	nail			
Date:	8	July	2010		